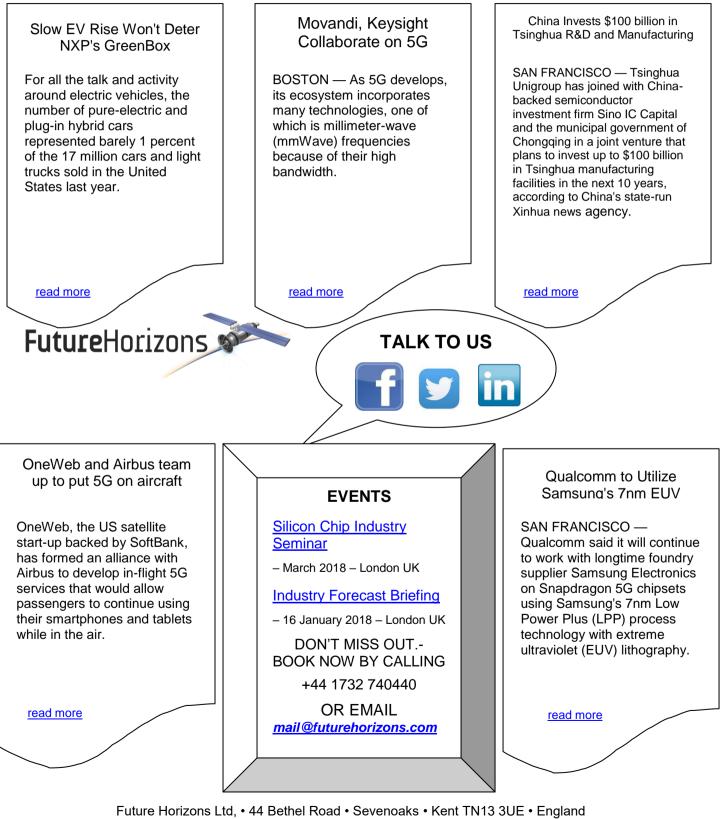
FutureHorizons

The Global Semiconductor Industry Analysts

FH MONDAY

26 February 2018



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Slow EV Rise Won't Deter NXP's GreenBox

MADISON, Wis. — For all the talk and activity around electric vehicles, the number of pure-electric and plug-in hybrid cars represented barely 1 percent of the 17 million cars and light trucks sold in the United States last year.

But sales shouldn't be seen as the only guide when assessing a global EV market where semiconductor companies hope to sell automotive chips. After all, car OEMs around the globe are investing billions of dollars into electric technologies to meet increasingly tougher emission rules.

Global momentum for vehicle electrification has motivated NXP Semiconductors to launch on Tuesday (Feb. 20th) its GreenBox development platform.

Movandi, Keysight Collaborate On 5G Mmwave

BOSTON — As 5G develops, its ecosystem incorporates many technologies, one of which is millimeter-wave (mmWave) frequencies because of their high bandwidth. Startup Movandi and Keysight Technologies have formed a collaboration in which Movandi uses Keysight test equipment combined with chambers and antennas from other sources to validate its BeamX mmWave front-end beamforming designs.

"Traditional RF designs won't work at mmWave frequencies," said Movandi co-CEO and COO, Maryam Rofougaran, in December 2017 at Keysight's 5G Tech Connect conference. "We need to overcome the challenges of signal blocking and penetration at mmWave frequencies." To that end, Movandi has developed an RFIC and beamforming antenna array that uses 64 antenna elements to steer beams toward their targets. The RFIC uses 64QAM modulation

China Invests \$100 Billion In Tsinghua R&D And Manufacturing

SAN FRANCISCO — Tsinghua Unigroup has joined with China-backed semiconductor investment firm Sino IC Capital and the municipal government of Chongqing in a joint venture that plans to invest up to \$100 billion in Tsinghua manufacturing facilities in the next 10 years, according to China's state-run Xinhua news agency.

The joint venture has an initial fund worth about \$15.8 billion, according to the report.

As part of the deal, Tsinghua Unigroup — China's largest chip company — agreed to build an industrial park in Chongqing, a municipality of about 28 million in southwestern China. The park will be home to Tsinghua Unigroup's R&D center and a manufacturing base for various ICs, according to the Xinhua report.

Oneweb And Airbus Team Up To Put 5G On Aircraft

OneWeb, the US satellite start-up backed by SoftBank, has formed an alliance with Airbus to develop in-flight 5G services that would allow passengers to continue using their smartphones and tablets while in the air.

Delta, the US airline, has also signed up to the 'Seamless Air Alliance', alongside telecoms companies Sprint, another SoftBank business, and Bharti Airtel, the Indian carrier. GoGo, which works with airlines on existing in-flight broadband systems, has also joined the group.

The move, to be revealed at this year's Mobile World Congress in Barcelona, is aimed at creating standards that bring mobile roaming on to planes, one of the few remaining black holes in terms of connectivity.

Qualcomm To Utilize Samsung's 7nm EUV Process

SAN FRANCISCO — Qualcomm said it will continue to work with longtime foundry supplier Samsung Electronics on Snapdragon 5G chipsets using Samsung's 7nm Low Power Plus (LPP) process technology with extreme ultraviolet (EUV) lithography.

Samsung aims to take the lead in putting long-delayed EUV into production, with plans to use it in its 7nm LPP process starting in the second half of this year. Other leading-edge chip makers-- including Intel, TSMC and Globalfoundries--are targeting EUV production sometime in 2019.

Qualcomm (San Diego) said using the 7nm LPP EUV process technology for Snapdragon 5G will give the chips a smaller footprint, providing handset OEMs with space to support larger batteries or slimmer designs. The process technology and design of the Snapdragon chips is expected to result in significant improvements in battery life, Qualcomm said.